SILICON (Si) POWER MOSFET ▲ CEB80N15



CEB80N15

150V ▲ 13.2mΩ ▲ 60A ▲ Si MOSFET

SILICON Si MOSFET ▲ SMD type N-channel enhancement mode UL94V-0 rated flame retardant epoxy TO263 (D2PAK) package ▲ MSL 3 Super high dense cell density for extremely low R_{DS(ON)} High power and current handling capability

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FREE

RoHS

REACH

MAXIMUM RATINGS

Parameter ($T_c = 25^{\circ}C$, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	150V
Gate-Source Voltage	V _{GS}	±20V
Continuous Drain Current at T _c = 25°C	I _D	76A
Continuous Drain Current at T _c = 100°C	I _D	55A
Pulsed Drain Current Note 1	IDM ^{Note 4}	304A
Maximum Power Dissipation at T _c = 25°C	PD	300W
Power Dissipation Derating above 25°C	ΔP _D	2W/°C
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +175°C

THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	0.5°C/W
Thermal Resistance, Junction-to-Ambient Note 2	R _{th_ja}	62.5°C/W

APPLICATIONS

Battery Management Systems	E-Bike	Industrial Control	Power Inverter	UPS
+ 4 -	50			

PIN DESCRIPTION

Circuit Diagram	Outline - Bottom View	Pin No.	Description
G (3)		1	Drain
G (3)		2	Source
S (2)		3	Gate

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ELECTRICAL CHARACTERISTICS A T_c = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_{D} = 250\mu A$	BV _{DSS}	150			V
Zero Gate Voltage Drain Current	V _{DS} = 150V, V _{GS} = 0V	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	I _{GSSF}			100	nA
Gate Body Leakage Current, Reverse	V_{GS} = -20V, V_{DS} = 0V	I _{GSSR}			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	V _{GS(th)}	2		4	V
Static Drain-Source On-Resistance	V_{GS} = 10V, I _D = 35A	R _{DS(ON)}		14	19	mΩ
Dynamic Characteristics Note 3						
Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 800kHz	C _{ISS}		8540		рF
Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 800 \text{kHz}$	Coss		455		pF
Reverse Transfer Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 800kHz	C _{RSS}		365		pF
Switching Characteristics Note 3						
Turn-On Delay Time	V_{DD} = 75V, V_{GS} = 10V, I_D = 38A, $R_{G(ext)}$ = 5 Ω	t _{D(ON)}		45		ns
Turn-On Rise Time	V_{DD} = 75V, V_{GS} = 10V, I_D = 38A, $R_{G(ext)}$ = 5 Ω	t _R		24		ns
Turn-Off Delay Time	V_{DD} = 75V, V_{GS} = 10V, I_D = 38A, $R_{G(ext)}$ = 5 Ω	t _{D(OFF)}		193		ns
Turn-Off Fall Time	V_{DD} = 75V, V_{GS} = 10V, I_D = 38A, $R_{G(ext)}$ = 5 Ω	t _F		33		ns
Total Gate Charge	$V_{DS} = 75V, V_{GS} = 10V, I_{D} = 38A$	Q _G		262		nC
Gate Source Charge	$V_{DS} = 75V, V_{GS} = 10V, I_D = 38A$	Q _{GS}		53		nC
Gate Drain Charge	V_{DS} = 75V, V_{GS} = 10V, I_{D} = 38A	\mathbf{Q}_{GD}		83		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode					76	А
Forward Current		ls			/0	А
Drain-Source Diode Forward Voltage ^{Note 2}	V _{GS} = 0V, I _S = 20A	V_{SD}			1.2	V

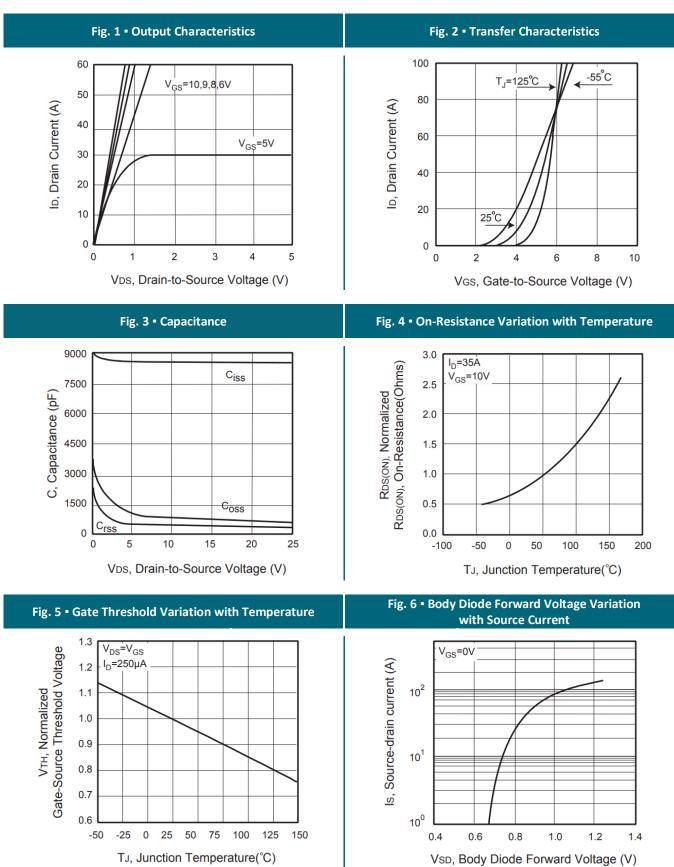
Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: Pulse width limited by safe operating area.



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REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE



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REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

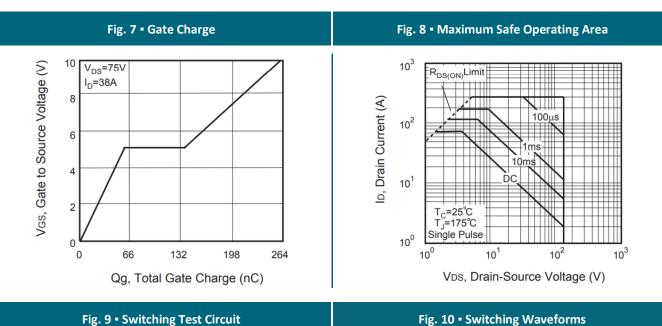
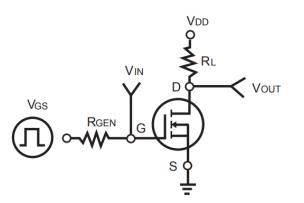


Fig. 9 - Switching Test Circuit



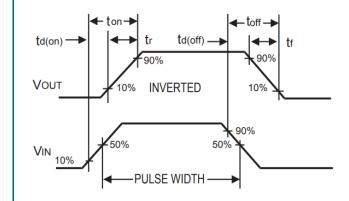
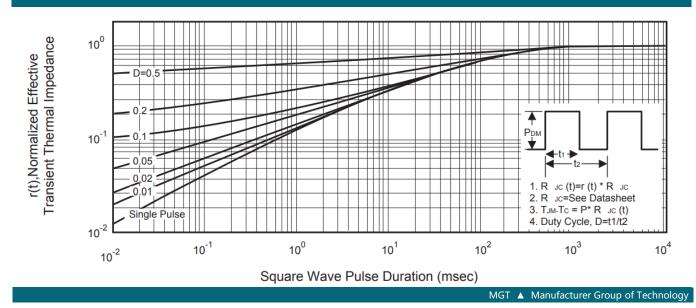


Fig. 11 • Normalized Thermal Transient Impedance Curve

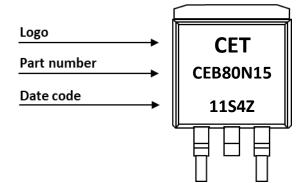


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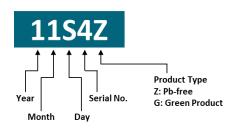


PART MARKING



DATE CODE

Example: 11S4Z



Coding list for "Day"

1	2	3	4	5	6	7	8	9	A
01	02	03	04	05	06	07	08	09	10
B	C	D	E	F	G	H	┃	J	K
11	12	13	14	15	16	17	18	19	20
L	M	N	0	P	Q	R	S	T	U
21	22	23	24	25	26	27	28	29	30
V 31									

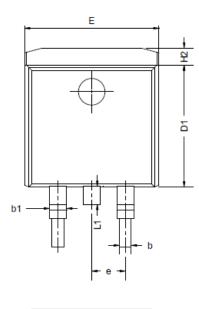
Coding list for "Month"

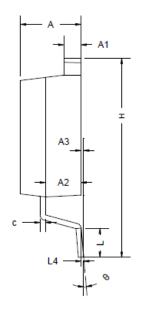
1 Jan		2 eb	3 Mar	4 Apr	5 May	6 Jun				
7 Jul		8 .ug	9 Sep	A Oct	B Nov	C Dec				
Coding list for "Year"										
	0	1	2		34					
2	020	202	1 202	22 20	23 20	24				
	5	6	7	' E	3 9					
2	025	202	5 202	27 20	28 20	29				

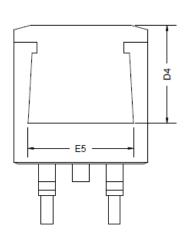
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PACKAGE OUTLINE







Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)	Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
А	4.37	4.57	4.77	E	9.86	10.16	10.36
A1	1.22	1.27	1.42	E5	7.06	-	-
A2	2.49	2.69	2.89	е		2.54 BSC	
A3	0.00	0.13	0.25	н	14.70	15.10	15.50
b	0.70	0.81	0.96	H2	1.07	1.27	1.47
b1	1.17	1.27	1.47	L	2.00	2.30	2.60
С	0.30	0.38	0.53	L1	1.40	1.55	1.70
D1	8.50	8.70	8.90	L4		0.25 BSC	
D4	6.60	-	-	θ	0°	5°	9°

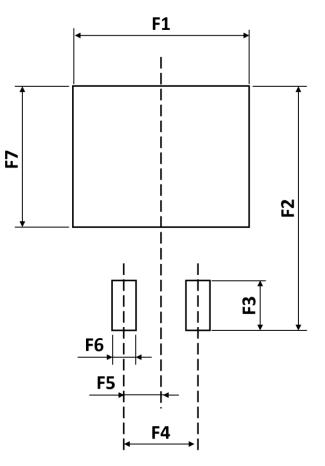
ORDERING INFORMATION

Part Number	Package	Packing	Reel Qty.	Inner Box Qty.	Outer Box Qty.
CEB80N15	TO263 (D2PAK)	Reel	800pcs	800pcs	6,400pcs





RECOMMENDED PAD LAYOUT



Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)	Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
F1	-	12.20	-	F5	-	2.54	-
F2	-	16.90	-	F6	-	1.60	-
F3	-	2.54	-	F7	-	9.75	-
F4	-	5.08	-				

Notes:

1. The suggested land pattern dimensions have been provided for reference only.

2. For further information, please reference document IPC-7351A.

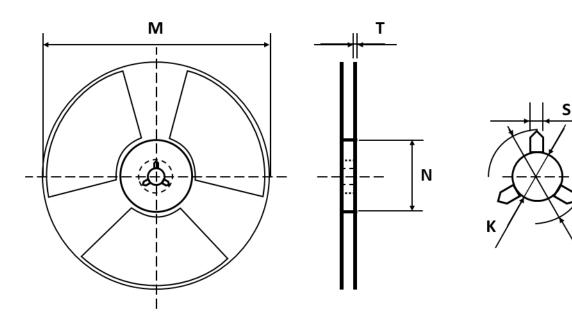
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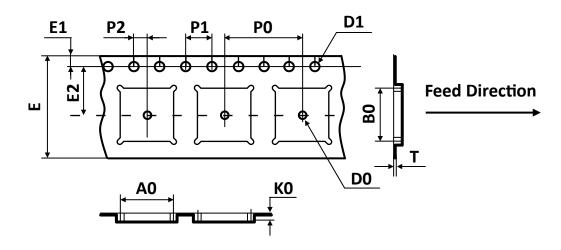


REEL DIMENSIONS All dimensions in mm



Tape Size	Reel Size	М	N	т	Н	К	S
		Ø330.00	Ø100.00	2.10	22.00	13.00	2.00
24mm	Ø330	±2.00	±0.50	±0.20	±0.50	+0.50	+0.50
		±2.00	±0.50	±0.20	±0.50	-0.20	-0.20

TAPE DIMENSIONS All dimensions in mm



Pack	kage	A0	B0	К0	D0	D1	E	E1	E2	P0	P1	P2	Т
TO2	263	10.80	16.30	4.85	1.50	1.55	24.00	1.75	11.50	16.00	4.00	2.00	0.35
(D ² P	PAK)	±0.10	±0.10	±0.10	±0.10	±0.05	±0.30	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05

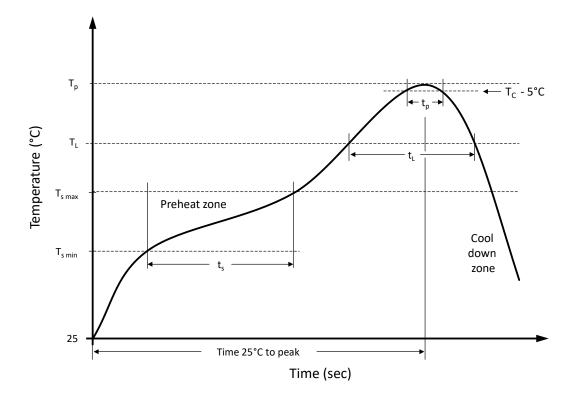


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RECOMMENDED REFLOW SOLDERING PROFILE



Recommended reflow soldering conditions ▲ **Refer to JEDEC J-STD-020E**

Profile Features		Sn-Pb Eutetic Assembly	Pb-Free Assembly
Preheat temperature min.	T_{smin}	100 °C	150 °C
Preheat temperature max.	$T_{s max}$	150 °C	200 °C
Preheat time t_s from $T_{s min}$ to $T_{s max}$	ts	120 seconds	120 seconds
Ramp-up rate (T _L to T _p)		max. 3 °C/second	max. 3 °C/second
Liquidous temperature	TL	183 °C	217 °C
Time t_L maintained above T_L	t∟	150 seconds max.	150 seconds max.
Peak package body temperature	Tp	235°C	260°C
Timeframe of within 5°C below and up to max actual peak body temperature	tp	20 seconds max.	30 seconds max.
Ramp-down rate (T_L to T_p)		max. 6 °C/second	max. 6 °C/second
Time 25°C to peak temperature		max. 6 minutes	max. 8 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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